L	Hits	Search Text	DB	Time stamp
Number				
1	147		USPAT;	2004/03/16
		same ((thin thinfilm (thin adj film))	US-PGPUB;	19:40
		same ((taper tapered) same ((silicon	EPO; JPO;	
		silicon semiconductor bulk gaas) with	DERWENT;	
		(substrate carrier))))	IBM_TDB	
2	203	(g	USPAT;	2004/03/16
		same ((thin thinfilm (thin adj film))	US-PGPUB;	19:41
		same ((taper tapered) same ((silicon	EPO; JPO;	
		silicon semiconductor bulk gaas) with	DERWENT;	
		(substrate carrier))))	IBM_TDB	
3	56	((through hole throughhole opening gap)	USPAT;	2004/03/16
		same ((thin thinfilm (thin adj film))	US-PGPUB;	19:41
		same ((taper tapered) same ((silicon	EPO; JPO;]
		silicon semiconductor bulk gaas) with	DERWENT;	
		(substrate carrier))))) not ((thourgh	IBM_TDB	
		hole thoughhole opening gap) same ((thin		
		thinfilm (thin adj film)) same ((taper		!
		tapered) same ((silicon silicon		
		semiconductor bulk gaas) with (substrate		
		carrier)))))		

L Number	Hits	Search Text	DB	Time stamp
1	517583	(silicon silicon semiconductor bulk gaas) with (substrate carruer)	USPAT; US-PGPUB; EPO; JPO;	2004/03/16 10:28
_			DERWENT; IBM_TDB	0004/00/45
2	3958	<pre>(taper tapered) same ((silicon silicon semiconductor bulk gaas) with (substrate carruer))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/16
3	496	(thin thinfilm (thin adj film)) same ((taper tapered) same ((silicon silicon semiconductor bulk gaas) with (substrate carruer)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/16 10:29
4	145	<pre>(thourgh hole thoughhole opening gap) same ((thin thinfilm (thin adj film)) same ((taper tapered) same ((silicon silicon semiconductor bulk gaas) with (substrate carruer))))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/16 10:30